

ABSTRACT

The present invention aims to improve the polishing rate during the polishing process of semiconductor substrates, hard disk substrates or the like by using a polishing composition containing silica particles, water, a basic substance and an inorganic salt, and by a polishing method using such a polishing composition.

This polishing composition can be produced by mixing silica particles, water, a basic substance and an inorganic salt, and it is also obtained by adding an inorganic salt into a conventionally known alkaline polishing composition containing silica particles.

As the inorganic salt, there is used an alkali metal salt or an ammonium salt such as KCl, K_2SO_4 , KNO_3 , NaCl, Na_2SO_4 , $NaNO_3$, NH_4Cl , NH_4NO_3 , and $(NH_4)_2SO_4$.

A polishing composition, wherein silica particles do not agglomerate when an inorganic salt is added, can improve the polishing rate significantly.